SCOPE OF ACCREDITATION

Electronics - Printed Boards

Eltek Ltd
Galis 20 Street
Petach-Tikva, 49101
Israel

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7119 Rev I - Nadcap Audit Criteria for Electronics Printed Boards (to be used on audits BEFORE 30-Jul-2023)

03–Company Information (mandatory)

04–General Information (mandatory)

05–Process Control (mandatory)

06– Engineering Source File Processing (mandatory)

07.1– Material Control: General (mandatory)

07.2– Material Control: PrePreg

08.1– Imaging – Photoprocess (mandatory)

08.2.1– DES – Developing Photoimageable Resist (mandatory

08.2.2– DES – Copper Etching of Inner Layers and Outer Layers (mandatory)

08.2.3– DES – Stripping of Resist Film and Etch–Resist Plating (mandatory)

08.2– Imaging – Develop–Etch–Strip (DES) and Strip–Etch–Strip (SES) (mandatory)

08.3– Etched Image Inspection (Manual or AOI) (mandatory)

09.1– Permanent Solder Mask: Solder Mask Application

09.2– Permanent Solder Mask: Solder Mask Exposing

09.3– Permanent Solder Mask: Solder Mask Develop and Cure

10– Oxide Coating / Oxide Replacement Coating

11– Material Lay–Up and Lamination (mandatory)

12.1– Drilling: Mechanical Drilling

12.2– Drilling: Laser Drilling– In House

12.4– Drilling: Post–Drill Cleaning and Etchback

13.1– Epoxy Hole Fill and Planarization: Non–Conductive and/or Conductive Epoxy Hole Fill

13.2– Epoxy Hole Fill and Planarization: Planarization

14.1– Copper Plating: Electroless Copper/Direct Metallization (mandatory)

14.2– Copper Plating: Electroplated Copper (mandatory)

15.1– Final Finishes: Hot Air Solder Leveling (HASL)

15.3– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish

15.6– Final Finishes: Wire Bondable Plating

16– Legend and Marking

17– Routing and Machining

18– Electrical Test – Functional (mandatory)

19– X–Ray Fluorescence (XRF)

20– Microsection Sample Selection Preparation and Inspection (mandatory)

21– Structural Integrity (mandatory)

22– Materials Lab (mandatory)

23– Chemistry Lab (mandatory)

24– Monthly Quality Conformance Testing

25– Final Validation (mandatory

26– Packaging (mandatory)

AC7119/2 Rev B - Nadcap Audit Criteria for Electronics Flexible and Rigid-Flexible Printed Boards (to be used on audits BEFORE 05-Nov-2023)

04– Handling

05– Material

06– Cover Material Application

07– Post–Drill Cleaning and Etchback

08– Stiffener Bonding

09– Strain Relief

10– Testing

11– Depanelization

12– Packaging

13– Final Validation

AC7119/5 - Nadcap Audit Criteria for Electronics High Frequency (MICROWAVE) Printed Boards